

Appl. No. 09/841,582
Amtd. Dated June 30, 2008
Reply to Office Action of December 31, 2007

REMARKS

Applicants have submitted this Request for Continued Examination so that the Examiner may consider the alternate claims as modified herein. Initially, in regard to the Examiner's rejection under 35 U.S.C. § 112, Applicants note that pasting on a substrate solely and only non-defective chips which are diced from a semiconductor wafer and selected is described throughout specification and specifically, for example, at page 9 at lines 28-30. Accordingly, in light of the foregoing, Applicants submit that there is more than ample disclosure and description of the recited limitations. Accordingly, Applicants submit that the limitations need not be removed from the claims.

Applicants respectfully submit that the prior art references of record, whether considered alone, or in combination, fail to either teach or suggest Applicants presently claimed invention. More specifically, by this amendment, Applicants have modified independent claim 6 to reflect the specific physical state of Applicants' instant innovation when the known good semiconductor chip structures have been secured to a substrate via a temporary adhesive material, this is described throughout specification and is specifically illustrated in Figure 1 D. As shown in this illustration, the temporary adhesive material 2 secures a plurality of known good die 3 to a substrate 1. A resin material 4 is used to encapsulate the known good die thereby forming a pseudo-wafer structure as described in specification.

Advantageously, this structure enables the known good die to be assembled to a common substrate for further processing, such as, for example, the addition of solder contacts to the electrodes. The use of the temporary adhesive material advantageously provides a

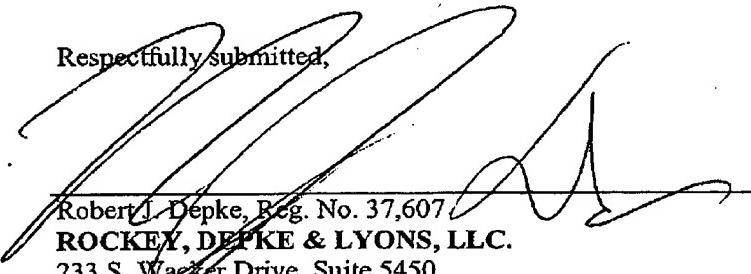
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convenient and economically feasible temporary structure that may be used for further processing of the known good die. Applicants respectfully submit the prior art references of record, whether considered alone, or in combination, fail to either teach or suggest this advance in the art.

Significantly, the use of the temporary adhesive structure provides a simple process wherein ultraviolet radiation may be used to release the pseudo-waiver structure for further processing. Applicants submit that none of the references of record teaches or even remotely suggests this innovation. Accordingly, in light of the foregoing, Applicants submit that all claims now stand in condition for allowance.

Respectfully submitted,

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